

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re Application of :
Daisuke Nakamura et al

Filed: Herewith :
For: HEAT DISSIPATING STRUCTURE OF PRINTED
CIRCUIT BOARD AND FABRICATING METHOD THEREOF

PRELIMINARY AMENDMENT A

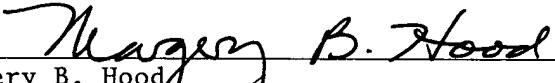
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Sir:

Please preliminarily amend the above-referenced application
as follows:

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Dated: November 25, 2003